



Material Content Data Sheet



Sales Product Name				SAK-TC267D-40F200N BC		Issued		1. August 2018	
MA#				MA001672874					
Package				PG-LFBGA-292-6		Weight*		934.11 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	17.078	1.83	1.83	18283	18283	
wire	noble metal	palladium	7440-05-3	0.014	0.00		15		
	non noble metal	copper	7440-50-8	1.396	0.15	0.15	1495	1510	
encapsulation	organic material	carbon black	1333-86-4	0.718	0.08		768		
	plastics	epoxy resin	-	49.521	5.30		53014		
	inorganic material	silicondioxide	60676-86-0	308.610	33.05	38.43	330378	384160	
substrate	plastics	epoxy resin	-	6.479	0.69		6936		
	inorganic material	bariumsulfate	7727-43-7	9.942	1.06		10643		
	plastics	acrylic resin	-	11.506	1.23		12317		
	inorganic material	aluminiumhydroxide	21645-51-2	53.265	5.70		57023		
	plastics	epoxy bismaleimide triazine resin	-	61.156	6.55		65470		
	inorganic material	glass fibre	-	82.857	8.87		88702		
	non noble metal	copper	7440-50-8	196.577	21.04	45.14	210443	451534	
plating	noble metal	gold	7440-57-5	1.231	0.13		1318		
	non noble metal	nickel	7440-02-0	3.370	0.36	0.49	3608	4926	
solderball	noble metal	silver	7440-22-4	4.457	0.48		4772		
	non noble metal	tin	7440-31-5	122.898	13.16	13.64	131567	136339	
glue	plastics	epoxy resin	-	0.758	0.08		812		
	noble metal	silver	7440-22-4	2.275	0.24	0.32	2436	3248	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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